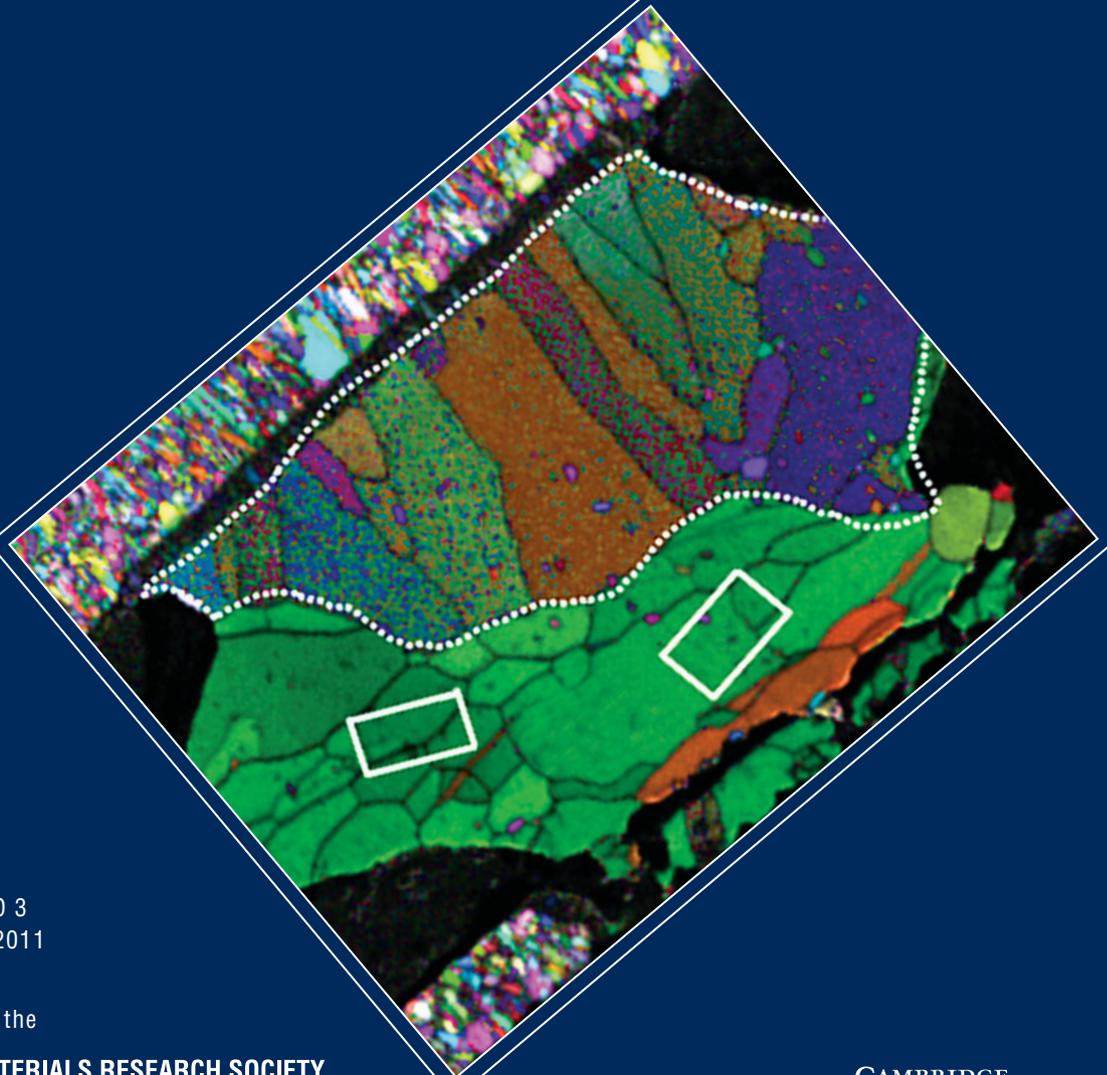




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Journal of MATERIALS RESEARCH

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Journal of MATERIALS RESEARCH

Volume 26, Number 3, February 14, 2011

MATERIALS COMMUNICATIONS

- 353–356 **Determination of the thickness of titanium films on glass substrate by nanoindentation tests** Tao Wen, Jianghong Gong, Zhijian Peng, Danyu Jiang, Chengbiao Wang, Zhiqiang Fu, Hezhuo Miao

ARTICLES

- 357–364 **Focused electron beam-induced deposition at cryogenic temperatures** M. Bresin, B.L. Thiel, M. Toth, K.A. Dunn, M. Toth
- 365–371 **Evolution of constitution, structure, and mechanical properties in Fe–Ti–Zr–B heterogeneous multiphase composites** Jin Man Park, Do Hyang Kim, Ki Buem Kim, Norbert Mattern, Jürgen Eckert
- 372–383 **Microstructure evolution of $Zr_2Al_3C_4$ in Cu matrix** J. Zhang, J.Y. Wang, Y.C. Zhou
- 384–394 **Prediction of effective thermal conductivities of woven fabric composites using unit cells at multiple length scales** Hongzhou Li, Shuguang Li, Yongchang Wang
- 395–406 **Effect of strain rate in severe plastic deformation on microstructure refinement and stored energies** Shashank Shekhar, Jiazhao Cai, Saurabh Basu, Sepideh Abolghasem, M. Ravi Shankar
- 407–415 **Effects of stacking fault energy on the thermal stability and mechanical properties of nanostructured Cu–Al alloys during thermal annealing** X.H. An, S. Qu, S.D. Wu, Z.F. Zhang
- 416–423 **Helium nanobubble release from Pd surface: An atomic simulation** Liang Wang, Wangyu Hu, Huiqiu Deng, Shifang Xiao, Jianyu Yang, Fei Gao, Howard L. Heinisch, Shilin Hu
- 424–429 **Synthesis of LiV_3O_8 nanorods and shape-dependent electrochemical performance** Peng Zhao, Dingsheng Wang, Jun Lu, Caiyun Nan, Xiaoling Xiao, Yadong Li
- 430–436 **Direct synthesis of tin oxide nanotubes on microhotplates using carbon nanotubes as templates** Prahalad Parthangal, Richard E. Cavicchi, Douglas C. Meier, Andrew Herzing, Michael R. Zachariah
- 437–442 **Current characterization and growth mechanism of anodic titania nanotube arrays** Chunbin Cao, Junlei Li, Xian Wang, Xueping Song, Zhaoqi Sun
- 443–448 **Influence of growth temperature on the structure, composition and bonding character of nitrogen-doped multiwalled carbon nanotubes** Yu Zhang, Lujun Pan, Bin Wen, Xiaoyang Song, Chenguang Liu, Tingju Li
- 449–454 **Transition of Bi embrittlement of SnBi/Cu joint couples with reflow temperature** H.F. Zou, Q.K. Zhang, Z.F. Zhang
- 455–466 **On the root cause of Kirkendall voiding in Cu_3Sn** Liang Yin, Peter Borgesen
- 467–474 **Effects of the crystallographic orientation of Sn on the electromigration of Cu/Sn–Ag–Cu/Cu ball joints** Kiju Lee, Keun-Soo Kim, Yutaka Tsukada, Katsuaki Sukanuma, Kimihiro Yamanaka, Soichi Kuritani, Minoru Ueshima
- 475–484 **Thermoelectric and transport properties of nanostructured Bi_2Te_3 by spark plasma sintering** Zhihui Zhang, Peter A. Sharma, Enrique J. Lavernia, Nancy Yang